

[Released on the web]

R20TS0556EJ0100

Rev.1.00

Apr. 01, 2020

RE Software Development Kit

RE01 1500KB Group CMSIS Driver Package Rev1.10

Outline

The RE Software Development Kit RE01 1500KB Group CMSIS Driver Package Rev1.10 is released on the web. The energy harvest control driver of the CMSIS-Core driver in this product has been improved to make the energy harvest function even more user-friendly.

This product is available free of charge.

1. Product Features

What is an RE01 1500KB Group CMSIS Driver Package?

The RE01 1500KB Group CMSIS Driver Package is a driver package that can be used to increase development efficiency. The package includes startup code and drivers for the peripheral functions so users can start system development immediately. In this package, ARM® CMSIS compliant API driver software and Renesas driver software are provided. Refer to the following URL for more information.

<https://www.renesas.com/re-cmsis>

2. Major Changes in RE01 1500KB Group CMSIS Driver Package Rev1.10

For major changes, refer to the application note for RE01 1500KB group CMSIS Driver Package Rev1.10.

<https://www.renesas.com/search/keyword-search.html#genre=document&q=r01an5355>

RE01 1500KB group CMSIS Driver Package Rev1.10

3. Supported Devices

RE family: RE01 1500KB group

4. Operating Environment

The recommended operating environment is as follows.

**Table1 List of Recommended Operating Environment**

IDE	Compiler	Debugger
IAR EWARM V8.4 or later (IAR Embedded Workbench® for ARM)	IAR V8.4 or later	IAR I-Jet
		SEGGER J-Link or J-Link OB
Renesas e <sup>2</sup> studio V7.0.0 or later	GCC V.6 GNU 6-2017-q2-update	SEGGER J-Link or J-Link OB

### 5. Obtaining the Product

Obtain the product from the URL below.

<https://www.renesas.com/re-cmsis>

Refer to the application note for more information.

<https://www.renesas.com/search/keyword-search.html#genre=document&q=r01an5355>

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**Revision History**

Rev.	Date	Description	
		Page	Summary
1.00	Apr.01.20	-	First edition issued

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